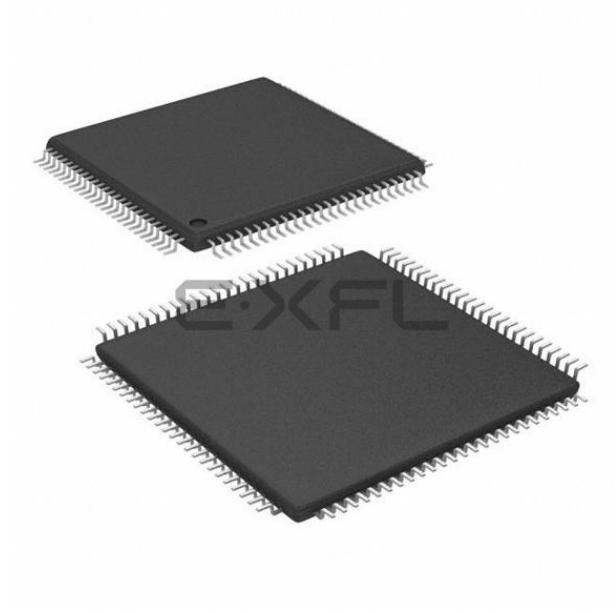
Microchip Technology - DSPIC33FJ64MC710AT-I/PF Datasheet



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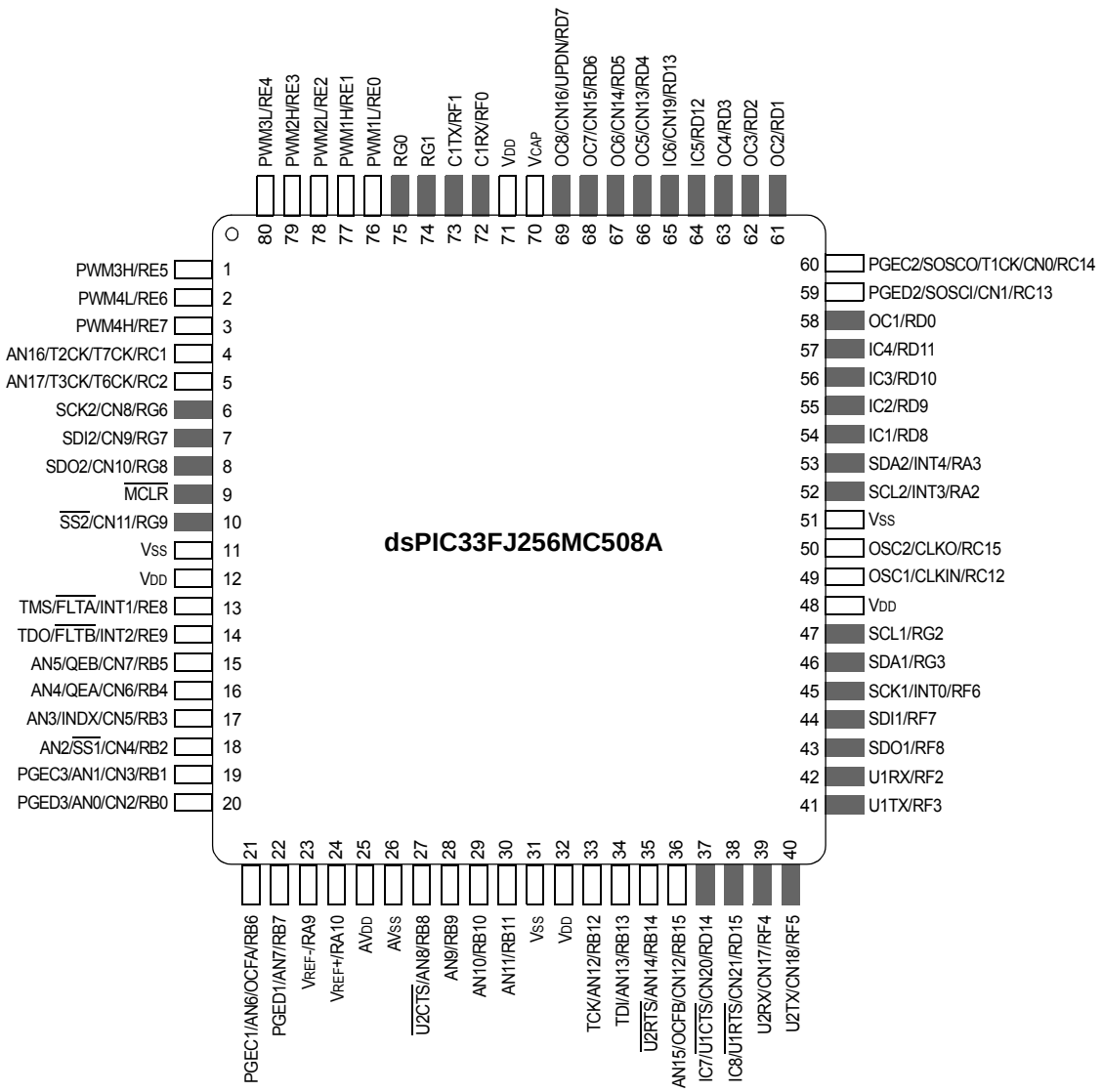
Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	dsPIC
Core Size	16-Bit
Speed	40 MIPs
Connectivity	CANbus, I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, Motor Control PWM, POR, PWM, QEI, WDT
Number of I/O	85
Program Memory Size	64KB (64K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	16K x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 24x10/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	100-TQFP
Supplier Device Package	100-TQFP (14x14)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33fj64mc710at-i-pf

Pin Diagrams (Continued)

80-Pin TQFP

■ = Pins are up to 5V tolerant



NOTES:

4.2.7 SOFTWARE STACK

In addition to its use as a working register, the W15 register in the dsPIC33FJXXXMCX06A/X08A/X10A devices is also used as a software Stack Pointer. The Stack Pointer always points to the first available free word and grows from lower to higher addresses. It pre-decrements for stack pops and post-increments for stack pushes, as shown in Figure 4-6. For a PC push during any CALL instruction, the MSb of the PC is zero-extended before the push, ensuring that the MSb is always clear.

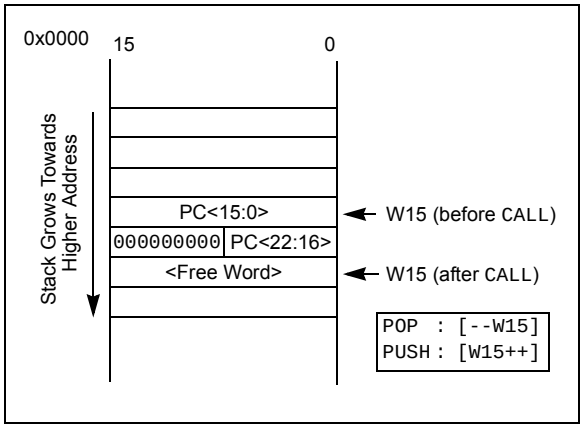
Note:	A PC push during exception processing concatenates the SRL register to the MSb of the PC prior to the push.

The Stack Pointer Limit register (SPLIM) associated with the Stack Pointer sets an upper address boundary for the stack. SPLIM is uninitialized at Reset. As is the case for the Stack Pointer, SPLIM<0> is forced to '0' because all stack operations must be word-aligned. Whenever an EA is generated using W15 as a source or destination pointer, the resulting address is compared with the value in SPLIM. If the contents of the Stack Pointer (W15) and the SPLIM register are equal and a push operation is performed, a stack error trap will not occur. The stack error trap will occur on a subsequent push operation. Thus, for example, if it is desirable to cause a stack error trap when the stack grows beyond address 0x2000 in RAM, initialize the SPLIM with the value 0x1FFE.

Similarly, a Stack Pointer underflow (stack error) trap is generated when the Stack Pointer address is found to be less than 0x0800. This prevents the stack from interfering with the Special Function Register (SFR) space.

A write to the SPLIM register should not be immediately followed by an indirect read operation using W15.

FIGURE 4-6: CALL STACK FRAME



4.2.8 DATA RAM PROTECTION FEATURE

The dsPIC33FJXXXMCX06A/X08A/X10A devices support data RAM protection features which enable segments of RAM to be protected when used in conjunction with Boot and Secure Code Segment Security. BSRAM (Secure RAM segment for BS) is accessible only from the Boot Segment Flash code when enabled. SSRAM (Secure RAM segment for RAM) is accessible only from the Secure Segment Flash code when enabled. See Table 4-1 for an overview of the BSRAM and SSRAM SFRs.

4.3 Instruction Addressing Modes

The addressing modes in Table 4-36 form the basis of the addressing modes optimized to support the specific features of individual instructions. The addressing modes provided in the MAC class of instructions are somewhat different from those in the other instruction types.

4.3.1 FILE REGISTER INSTRUCTIONS

Most file register instructions use a 13-bit address field (f) to directly address data present in the first 8192 bytes of data memory (Near Data Space). Most file register instructions employ a working register, W0, which is denoted as WREG in these instructions. The destination is typically either the same file register or WREG (with the exception of the MUL instruction), which writes the result to a register or register pair. The MOV instruction allows additional flexibility and can access the entire data space.

4.3.2 MCU INSTRUCTIONS

The 3-operand MCU instructions are of the following form:

Operand 3 = Operand 1 <function> Operand 2

where Operand 1 is always a working register (i.e., the addressing mode can only be Register Direct) which is referred to as Wb. Operand 2 can be a W register fetched from data memory or a 5-bit literal. The result location can be either a W register or a data memory location. The following addressing modes are supported by MCU instructions:

- Register Direct
- Register Indirect
- Register Indirect Post-Modified
- Register Indirect Pre-Modified
- 5-Bit or 10-Bit Literal

Note:	Not all instructions support all the addressing modes given above. Individual instructions may support different subsets of these addressing modes.

4.6.2 DATA ACCESS FROM PROGRAM MEMORY USING TABLE INSTRUCTIONS

The TBLRDL and TBLWTL instructions offer a direct method of reading or writing the lower word of any address within the program space without going through data space. The TBLRDH and TBLWTH instructions are the only method to read or write the upper 8 bits of a program space word as data.

The PC is incremented by two for each successive 24-bit program word. This allows program memory addresses to directly map to data space addresses. Program memory can thus be regarded as two 16-bit word wide address spaces residing side by side, each with the same address range. TBLRDL and TBLWTL access the space which contains the least significant data word, and TBLRDH and TBLWTH access the space which contains the upper data byte.

Two table instructions are provided to move byte or word-sized (16-bit) data to and from program space. Both function as either byte or word operations.

1. TBLRDL (Table Read Low): In Word mode, it maps the lower word of the program space location (P<15:0>) to a data address (D<15:0>).

   In Byte mode, either the upper or lower byte of the lower program word is mapped to the lower byte of a data address. The upper byte is selected when byte select is '1'; the lower byte is selected when it is '0'.

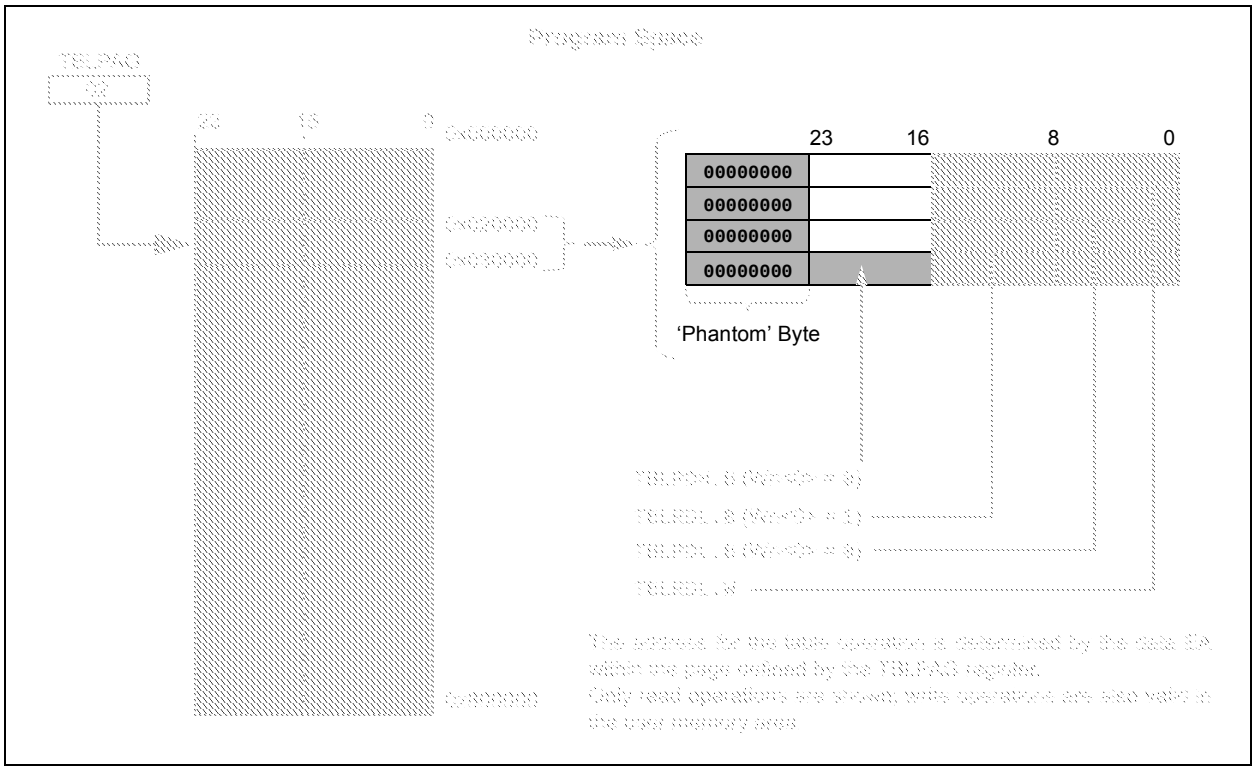
2. TBLRDH (Table Read High): In Word mode, it maps the entire upper word of a program address (P<23:16>) to a data address. Note that D<15:8>, the 'phantom' byte, will always be '0'.

   In Byte mode, it maps the upper or lower byte of the program word to D<7:0> of the data address, as above. Note that the data will always be '0' when the upper 'phantom' byte is selected (byte select = 1).

In a similar fashion, two table instructions, TBLWTH and TBLWTL, are used to write individual bytes or words to a program space address. The details of their operation are explained in **Section 5.0 "Flash Program Memory"**.

For all table operations, the area of program memory space to be accessed is determined by the Table Page register (TBLPAG). TBLPAG covers the entire program memory space of the device, including user and configuration spaces. When TBLPAG<7> = 0, the table page is located in the user memory space. When TBLPAG<7> = 1, the page is located in configuration space.

FIGURE 4-10: ACCESSING PROGRAM MEMORY WITH TABLE INSTRUCTIONS



5.4.1 PROGRAMMING ALGORITHM FOR FLASH PROGRAM MEMORY

The user can program one row of program Flash memory at a time. To do this, it is necessary to erase the 8-row erase page that contains the desired row. The general process is as follows:

1. Read eight rows of program memory (512 instructions) and store it in data RAM.
2. Update the program data in RAM with the desired new data.
3. Erase the block (see Example 5-1):
   a) Set the NVMOP bits (NVMCON<3:0>) to '0010' to configure for block erase. Set the ERASE (NVMCON<6>) and WREN (NVMCON<14>) bits.
   b) Write the starting address of the page to be erased into the TBLPAG and W registers.
   c) Write 0x55 to NVMKEY.
   d) Write 0xAA to NVMKEY.
   e) Set the WR bit (NVMCON<15>). The erase cycle begins and the CPU stalls for the duration of the erase cycle. When the erase is done, the WR bit is cleared automatically.
4. Write the first 64 instructions from data RAM into the program memory buffers (see Example 5-2).
5. Write the program block to Flash memory:
   a) Set the NVMOP bits to '0001' to configure for row programming. Clear the ERASE bit and set the WREN bit.
   b) Write 0x55 to NVMKEY.
   c) Write 0xAA to NVMKEY.
   d) Set the WR bit. The programming cycle begins and the CPU stalls for the duration of the write cycle. When the write to Flash memory is done, the WR bit is cleared automatically.
6. Repeat steps 4 and 5 using the next available 64 instructions from the block in data RAM by incrementing the value in TBLPAG until all 512 instructions are written back to Flash memory.

For protection against accidental operations, the write initiate sequence for NVMKEY must be used to allow any erase or program operation to proceed. After the programming command has been executed, the user must wait for the programming time until programming is complete. The two instructions following the start of the programming sequence should be NOPs, as shown in Example 5-3.

EXAMPLE 5-1: ERASING A PROGRAM MEMORY PAGE

```
; Set up NVMCON for block erase operation
        MOV     #0x4042, W0                 ;
        MOV     W0, NVMCON                  ; Initialize NVMCON
; Init pointer to row to be ERASED
        MOV     #tblpage(PROG_ADDR), W0     ;
        MOV     W0, TBLPAG                  ; Initialize PM Page Boundary SFR
        MOV     #tbloffset(PROG_ADDR), W0   ; Initialize in-page EA[15:0] pointer
        TBLWTL  W0, [W0]                    ; Set base address of erase block
        DISI    #5                          ; Block all interrupts with priority <7
                                            ; for next 5 instructions
        MOV     #0x55, W0
        MOV     W0, NVMKEY                  ; Write the 55 key
        MOV     #0xAA, W1                   ;
        MOV     W1, NVMKEY                  ; Write the AA key
        BSET    NVMCON, #WR                 ; Start the erase sequence
        NOP                                 ; Insert two NOPs after the erase
        NOP                                 ; command is asserted
```

REGISTER 6-1: RCON: RESET CONTROL REGISTER(1) (CONTINUED)

bit 1 **BOR:** Brown-out Reset Flag bit
1 = A Brown-out Reset has occurred
0 = A Brown-out Reset has not occurred

bit 0 **POR:** Power-on Reset Flag bit
1 = A Power-on Reset has occurred
0 = A Power-on Reset has not occurred

Note 1: All of the Reset status bits may be set or cleared in software. Setting one of these bits in software does not cause a device Reset.

2: If the FWDTEN Configuration bit is '1' (unprogrammed), the WDT is always enabled, regardless of the SWDTEN bit setting.

3: For dsPIC33FJ256MCX06A/X08A/X10A devices, this bit is unimplemented and reads back a programmed value.

7.3 Interrupt Control and Status Registers

dsPIC33FJXXXMCX06A/X08A/X10A devices implement a total of 30 registers for the interrupt controller:

- INTCON1
- INTCON2
- IFS0 through IFS4
- IEC0 through IEC4
- IPC0 through IPC17
- INTTREG

Global interrupt control functions are controlled from INTCON1 and INTCON2. INTCON1 contains the Interrupt Nesting Disable bit (NSTDIS) as well as the control and status flags for the processor trap sources. The INTCON2 register controls the external interrupt request signal behavior and the use of the Alternate Interrupt Vector Table.

The IFS registers maintain all of the interrupt request flags. Each source of interrupt has a status bit, which is set by the respective peripherals or external signal and is cleared via software.

The IEC registers maintain all of the interrupt enable bits. These control bits are used to individually enable interrupts from the peripherals or external signals.

The IPC registers are used to set the interrupt priority level for each source of interrupt. Each user interrupt source can be assigned to one of eight priority levels.

The INTTREG register contains the associated interrupt vector number and the new CPU interrupt priority level, which are latched into vector number (VECNUM<6:0>) and Interrupt level bit (ILR<3:0>) fields in the INTTREG register. The new interrupt priority level is the priority of the pending interrupt.

The interrupt sources are assigned to the IFSx, IECx and IPCx registers in the same sequence that they are listed in Table 7-1. For example, the INT0 (External Interrupt 0) is shown as having vector number 8 and a natural order priority of 0. Thus, the INT0IF bit is found in IFS0<0>, the INT0IE bit in IEC0<0> and the INT0IP bits in the first position of IPC0 (IPC0<2:0>).

Although they are not specifically part of the interrupt control hardware, two of the CPU Control registers contain bits that control interrupt functionality. The CPU STATUS register, SR, contains the IPL<2:0> bits (SR<7:5>). These bits indicate the current CPU interrupt priority level. The user can change the current CPU priority level by writing to the IPL bits.

The CORCON register contains the IPL3 bit, which together with IPL<2:0>, also indicates the current CPU priority level. IPL3 is a read-only bit so that trap events cannot be masked by the user software.

All Interrupt registers are described in Register 7-1 through Register 7-32 in the following pages.

REGISTER 7-6: IFS1: INTERRUPT FLAG STATUS REGISTER 1 (CONTINUED)

bit 3 **CNIF:** Input Change Notification Interrupt Flag Status bit
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

bit 2 **Unimplemented:** Read as '0'

bit 1 **MI2C1IF:** I2C1 Master Events Interrupt Flag Status bit
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

bit 0 **SI2C1IF:** I2C1 Slave Events Interrupt Flag Status bit
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

REGISTER 8-5: DMAxPAD: DMA CHANNEL x PERIPHERAL ADDRESS REGISTER(1)

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
PAD<15:8>							
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
PAD<7:0>							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-0 **PAD<15:0>:** Peripheral Address Register bits

Note 1: If the channel is enabled (i.e., active), writes to this register may result in unpredictable behavior of the DMA channel and should be avoided.

REGISTER 8-6: DMAxCNT: DMA CHANNEL x TRANSFER COUNT REGISTER(1)

U-0	U-0	U-0	U-0	U-0	U-0	R/W-0	R/W-0
—	—	—	—	—	—	CNT<9:8>(2)	
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
CNT<7:0>(2)							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-10 **Unimplemented:** Read as '0'

bit 9-0 **CNT<9:0>:** DMA Transfer Count Register bits(2)

Note 1: If the channel is enabled (i.e., active), writes to this register may result in unpredictable behavior of the DMA channel and should be avoided.

2: Number of DMA transfers = CNT<9:0> + 1.

NOTES:

REGISTER 10-3: PMD3: PERIPHERAL MODULE DISABLE CONTROL REGISTER 3

R/W-0	R/W-0	R/W-0	R/W-0	U-0	U-0	U-0	U-0
T9MD	T8MD	T7MD	T6MD	—	—	—	—
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	U-0	R/W-0	R/W-0
—	—	—	—	—	—	I2C2MD	AD2MD(1)
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **T9MD:** Timer9 Module Disable bit
1 = Timer9 module is disabled
0 = Timer9 module is enabled

bit 14 **T8MD:** Timer8 Module Disable bit
1 = Timer8 module is disabled
0 = Timer8 module is enabled

bit 13 **T7MD:** Timer7 Module Disable bit
1 = Timer7 module is disabled
0 = Timer7 module is enabled

bit 12 **T6MD:** Timer6 Module Disable bit
1 = Timer6 module is disabled
0 = Timer6 module is enabled

bit 11-2 **Unimplemented:** Read as '0'

bit 1 **I2C2MD:** I2C2 Module Disable bit
1 = I2C2 module is disabled
0 = I2C2 module is enabled

bit 0 **AD2MD:** AD2 Module Disable bit(1)
1 = AD2 module is disabled
0 = AD2 module is enabled

Note 1: The PCFGx bits have no effect if the ADC module is disabled by setting this bit. In this case, all port pins multiplexed with ANx will be in Digital mode.

NOTES:

REGISTER 16-6: PWMxCON2: PWMx CONTROL REGISTER 2

U-0	U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	—	—	SEVOPS<3:0>			
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	R/W-0	R/W-0	R/W-0
—	—	—	—	—	IUE	OSYNC	UDIS
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-12 **Unimplemented:** Read as '0'

bit 11-8 **SEVOPS<3:0>:** PWM Special Event Trigger Output Postscale Select bits

1111 = 1:16 postscale
•
•
0001 = 1:2 postscale
0000 = 1:1 postscale

bit 7-3 **Unimplemented:** Read as '0'

bit 2 **IUE:** Immediate Update Enable bit

1 = Updates to the active PDC registers are immediate
0 = Updates to the active PDC registers are synchronized to the PWM time base

bit 1 **OSYNC:** Output Override Synchronization bit

1 = Output overrides via the OVDCON register are synchronized to the PWM time base
0 = Output overrides via the OVDCON register occur on next TCY boundary

bit 0 **UDIS:** PWM Update Disable bit

1 = Updates from Duty Cycle and Period Buffer registers are disabled
0 = Updates from Duty Cycle and Period Buffer registers are enabled

21.3 Modes of Operation

The CAN module can operate in one of several operation modes selected by the user. These modes include:

- Initialization Mode
- Disable Mode
- Normal Operation Mode
- Listen Only Mode
- Listen All Messages Mode
- Loopback Mode

Modes are requested by setting the REQOP<2:0> bits (CiCTRL1<10:8>). Entry into a mode is Acknowledged by monitoring the OPMODE<2:0> bits (CiCTRL1<7:5>). The module will not change the mode and the OPMODE bits until a change in mode is acceptable, generally during bus Idle time, which is defined as at least 11 consecutive recessive bits.

21.3.1 INITIALIZATION MODE

In the Initialization mode, the module will not transmit or receive. The error counters are cleared and the interrupt flags remain unchanged. The programmer will have access to Configuration registers that are access restricted in other modes. The module will protect the user from accidentally violating the CAN protocol through programming errors. All registers which control the configuration of the module cannot be modified while the module is on-line. The CAN module will not be allowed to enter the Configuration mode while a transmission is taking place. The Configuration mode serves as a lock to protect the following registers:

- All Module Control Registers
- Baud Rate and Interrupt Configuration Registers
- Bus Timing Registers
- Identifier Acceptance Filter Registers
- Identifier Acceptance Mask Registers

21.3.2 DISABLE MODE

In Disable mode, the module will not transmit or receive. The module has the ability to set the WAKIF bit due to bus activity, however, any pending interrupts will remain and the error counters will retain their value.

If the REQOP<2:0> bits (CiCTRL1<10:8>) = 001, the module will enter the Module Disable mode. If the module is active, the module will wait for 11 recessive bits on the CAN bus, detect that condition as an Idle bus, then accept the module disable command. When the OPMODE<2:0> bits (CiCTRL1<7:5>) = 001, that indicates whether the module successfully went into Module Disable mode. The I/O pins will revert to normal I/O function when the module is in the Module Disable mode.

The module can be programmed to apply a low-pass filter function to the CiRX input line while the module or the CPU is in Sleep mode. The WAKFIL bit (CiCFG2<14>) enables or disables the filter.

Note:	Typically, if the CAN module is allowed to transmit in a particular mode of operation and a transmission is requested immediately after the CAN module has been placed in that mode of operation, the module waits for 11 consecutive recessive bits on the bus before starting transmission. If the user switches to Disable mode within this 11-bit period, then this transmission is aborted and the corresponding TXABT bit is set, and the TXREQ bit is cleared.

21.3.3 NORMAL OPERATION MODE

Normal Operation mode is selected when REQOP<2:0> = 000. In this mode, the module is activated and the I/O pins will assume the CAN bus functions. The module will transmit and receive CAN bus messages via the CiTX and CiRX pins.

21.3.4 LISTEN ONLY MODE

If the Listen Only mode is activated, the module on the CAN bus is passive. The transmitter buffers revert to the port I/O function. The receive pins remain inputs. For the receiver, no error flags or Acknowledge signals are sent. The error counters are deactivated in this state. The Listen Only mode can be used for detecting the baud rate on the CAN bus. To use this, it is necessary that there are at least two further nodes that communicate with each other.

21.3.5 LISTEN ALL MESSAGES MODE

The module can be set to ignore all errors and receive any message. The Listen All Messages mode is activated by setting REQOP<2:0> = 111. In this mode, the data which is in the message assembly buffer until the time an error occurred, is copied in the receive buffer and can be read via the CPU interface.

21.3.6 LOOPBACK MODE

If the Loopback mode is activated, the module will connect the internal transmit signal to the internal receive signal at the module boundary. The transmit and receive pins revert to their port I/O function.

26.1 DC Characteristics

TABLE 26-1: OPERATING MIPS vs. VOLTAGE

Param No.	VDD Range (in Volts)	Temp Range (in °C)	Max MIPS
			dsPIC33FJXXXMCX06A/X08A/X10A
—	VBOR-3.6V(1)	-40°C to +85°C	40
—	VBOR-3.6V(1)	-40°C to +125°C	40

Note 1: Device is functional at VBORMIN < VDD < VDDMIN. Analog modules such as the ADC will have degraded performance. Device functionality is tested but not characterized. Refer to parameter BO10 in Table 26-11 for the minimum and maximum BOR values.

TABLE 26-2: THERMAL OPERATING CONDITIONS

Rating	Symbol	Min	Typ	Max	Unit
dsPIC33FJXXXMCX06A/X08A/X10A					
Operating Junction Temperature Range	TJ	-40	—	+125	°C
Operating Ambient Temperature Range	TA	-40	—	+85	°C
Extended Temperature Devices					
Operating Junction Temperature Range	TJ	-40	—	+155	°C
Operating Ambient Temperature Range	TA	-40	—	+125	°C
Power Dissipation: Internal Chip Power Dissipation: PINT = VDD x (IDD – Σ IOH) I/O Pin Power Dissipation: I/O = Σ ({VDD – VOH} x IOH) + Σ (VOL x IOL)	PD	PINT + PI/O			W
Maximum Allowed Power Dissipation	PDMAX	(TJ – TA)/θJA			W

TABLE 26-3: THERMAL PACKAGING CHARACTERISTICS

Characteristic	Symbol	Typ	Max	Unit	Notes
Package Thermal Resistance, 100-pin TQFP (14x14x1 mm)	θJA	40	—	°C/W	1
Package Thermal Resistance, 100-pin TQFP (12x12x1 mm)	θJA	40	—	°C/W	1
Package Thermal Resistance, 80-pin TQFP (12x12x1 mm)	θJA	40	—	°C/W	1
Package Thermal Resistance, 64-pin TQFP (10x10x1 mm)	θJA	40	—	°C/W	1
Package Thermal Resistance, 64-pin QFN (9x9x0.9 mm)	θJA	28	—	°C/W	1

Note 1: Junction to ambient thermal resistance, Theta-JA (θJA) numbers are achieved by package simulations.

TABLE 26-39: SPIx SLAVE MODE (FULL-DUPLEX, CKE = 0, CKP = 0, SMP = 0) TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 2.4V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic(1)**	**Min**	**Typ(2)**	**Max**	**Units**	**Conditions**
SP70	TscP	Maximum SCK Input Frequency	—	—	11	MHz	See **Note 3**
SP72	TscF	SCKx Input Fall Time	—	—	—	ns	See parameter DO32 and **Note 4**
SP73	TscR	SCKx Input Rise Time	—	—	—	ns	See parameter DO31 and **Note 4**
SP30	TdoF	SDOx Data Output Fall Time	—	—	—	ns	See parameter DO32 and **Note 4**
SP31	TdoR	SDOx Data Output Rise Time	—	—	—	ns	See parameter DO31 and **Note 4**
SP35	TscH2doV, TscL2doV	SDOx Data Output Valid after SCKx Edge	—	6	20	ns	—
SP36	TdoV2scH, TdoV2scL	SDOx Data Output Setup to First SCKx Edge	30	—	—	ns	—
SP40	TdiV2scH, TdiV2scL	Setup Time of SDIx Data Input to SCKx Edge	30	—	—	ns	—
SP41	TscH2diL, TscL2diL	Hold Time of SDIx Data Input to SCKx Edge	30	—	—	ns	—
SP50	TssL2scH, TssL2scL	$\overline{SSx}$ ↓ to SCKx ↑ or SCKx Input	120	—	—	ns	—
SP51	TssH2doZ	$\overline{SSx}$ ↑to SDOx Output High-Impedance(4)	10	—	50	ns	—
SP52	TscH2ssH TscL2ssH	$\overline{SSx}$ after SCKx Edge	1.5 TCY + 40	—	—	ns	See **Note 4**

Note 1: These parameters are characterized, but are not tested in manufacturing.

2: Data in "Typ" column is at 3.3V, 25°C unless otherwise stated.

3: The minimum clock period for SCKx is 91 ns. Therefore, the SCK clock generated by the Master must not violate this specificiation.

4: Assumes 50 pF load on all SPIx pins.

TABLE 27-12: SPIx MODULE SLAVE MODE (CKE = 0) TIMING REQUIREMENTS

AC CHARACTERISTICS		Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +150°C for High Temperature					
Param No.	**Symbol**	**Characteristic(1)**	**Min**	**Typ**	**Max**	**Units**	**Conditions**
HSP35	TscH2doV, TscL2doV	SDOx Data Output Valid after SCKx Edge	—	—	35	ns	—
HSP40	TdiV2scH, TdiV2scL	Setup Time of SDIx Data Input to SCKx Edge	25	—	—	ns	—
HSP41	TscH2diL, TscL2diL	Hold Time of SDIx Data Input to SCKx Edge	25	—	—	ns	—
HSP51	TssH2doZ	$\overline{SSx}$ ↑ to SDOx Output High-Impedance	15	—	55	ns	See **Note 2**

Note 1: These parameters are characterized but not tested in manufacturing.

2: Assumes 50 pF load on all SPIx pins.

TABLE 27-13: SPIx MODULE SLAVE MODE (CKE = 1) TIMING REQUIREMENTS

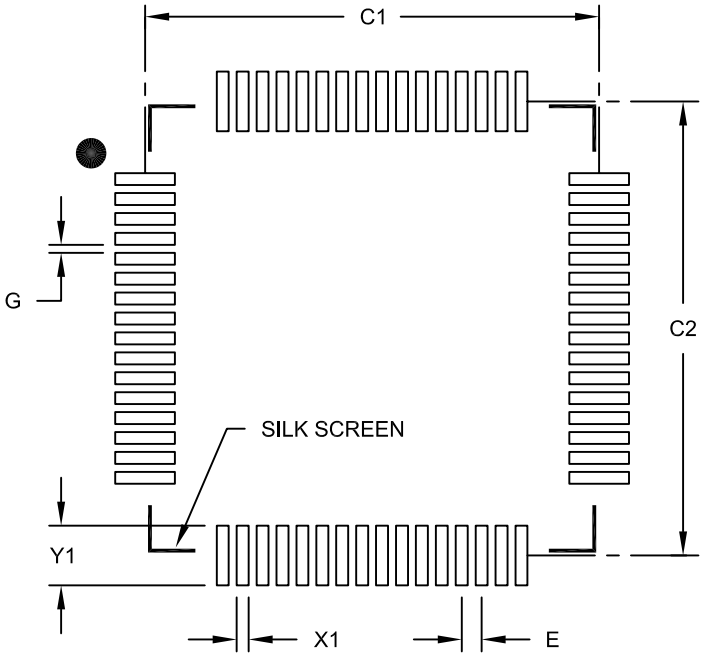
AC CHARACTERISTICS		Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +150°C for High Temperature					
Param No.	**Symbol**	**Characteristic(1)**	**Min**	**Typ**	**Max**	**Units**	**Conditions**
HSP35	TscH2doV, TscL2doV	SDOx Data Output Valid after SCKx Edge	—	—	35	ns	—
HSP40	TdiV2scH, TdiV2scL	Setup Time of SDIx Data Input to SCKx Edge	25	—	—	ns	—
HSP41	TscH2diL, TscL2diL	Hold Time of SDIx Data Input to SCKx Edge	25	—	—	ns	—
HSP51	TssH2doZ	$\overline{SSx}$ ↑ to SDOx Output High-Impedance	15	—	55	ns	See **Note 2**
HSP60	TssL2doV	SDOx Data Output Valid after $\overline{SSx}$ Edge	—	—	55	ns	—

Note 1: These parameters are characterized but not tested in manufacturing.

2: Assumes 50 pF load on all SPIx pins.

64-Lead Plastic Thin Quad Flatpack (PT) 10x10x1 mm Body, 2.00 mm Footprint [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E		0.50 BSC	
Contact Pad Spacing	C1		11.40	
Contact Pad Spacing	C2		11.40	
Contact Pad Width (X64)	X1			0.30
Contact Pad Length (X64)	Y1			1.50
Distance Between Pads	G	0.20		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2085B

Revision C (March 2011)

This revision includes typographical and formatting changes throughout the data sheet text. In addition, all instances of VDDCORE have been removed.

All other major changes are referenced by their respective section in the following table.

TABLE B-2: MAJOR SECTION UPDATES

Section Name	Update Description
Section 2.0 "Guidelines for Getting Started with 16-bit Digital Signal Controllers"	Updated the title of **Section 2.3 "CPU Logic Filter Capacitor Connection (VCAP)"**. The frequency limitation for device PLL start-up conditions was updated in **Section 2.7 "Oscillator Value Conditions on Device Start-up"**. The second paragraph in **Section 2.9 "Unused I/Os"** was updated.
Section 4.0 "Memory Organization"	The All Resets values for the following SFRs in the Timer Register Map were changed (see Table 4-6): • TMR1 • TMR2 • TMR3 • TMR4 • TMR5 • TMR6 • TMR7 • TMR8 • TMR9
Section 9.0 "Oscillator Configuration"	Added Note 3 to the OSCCON: Oscillator Control Register (see Register 9-1). Added Note 2 to the CLKDIV: Clock Divisor Register (see Register 9-2). Added Note 1 to the PLLFBD: PLL Feedback Divisor Register (see Register 9-3). Added Note 2 to the OSCTUN: FRC Oscillator Tuning Register (see Register 9-4).
Section 22.0 "10-bit/12-bit Analog-to-Digital Converter (ADC)"	Updated the VREFL references in the ADC1 module block diagram (see Figure 22-1).
Section 23.0 "Special Features"	Added a new paragraph and removed the third paragraph in **Section 23.1 "Configuration Bits"**. Added the column "RTSP Effects" to the Configuration Bits Descriptions (see Table 23-2).

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